This Sheet Has Been Replaced

Abstract

A tape carrier for a semiconductor device comprising a flexible insulation tape having via holes for a solder ball, a metal wiring layer formed on one surface of the insulation tape, the via halls for the solder balls having an opening on the other surface of the insulating tape, and a metal brace formed on the periphery of the opening of the respective via holes, wherein the metal brace is formed in a ring-shape provided with a cutout opening having a width up to 4 % of the circumferential length of the periphery, or comprises a plurality of arcuate shape portions, such that gaps are simetorically provided and positioned between the arcuate shape portions,, and that the total width of the gaps is up to 40 % of the circumferential length of the periphery, and wherein the metal braces have a surface to which Ni plating is applied, and Au plating is applied to the Ni plating.

FIG. 1